

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): TAKAHASHI et al

Serial No.: TBD

Filed: June 25, 2003

For: Solvent-Free Thermosetting Resin Composition,
Process For Producing The Same, And Product
Therefrom

INFORMATION DISCLOSURE STATEMENT
UNDER 37 CFR §1.97 & §1.98

Mail Stop
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

June 25, 2003

Sir:

Pursuant to Applicants' duty of disclosure, enclosed please find a List, on a form substantially equivalent to Form PTO-1449, of documents submitted for consideration by the Examiner in connection with a prior application of the above-identified application, Application No. 10/182,181, filed July 25, 2002. Also on this List, and enclosed herewith, is U.S. Patent No. 5,623,026 to Buekers, et al., cited in the International (PCT) Search Report in connection with the corresponding International application to No. 10/182,181 (that is, No. PCT/JP00/00507).

This Information Disclosure Statement is being submitted concurrently with the filing of the above-identified application. Clearly, requirements of 37 CFR § 1.97(b) are satisfied.

To the extent that the documents on the enclosed list are not in English, it is respectfully submitted that requirements of 37 CFR § 1.98(a)(3) are satisfied by discussion in the specification of the above-identified application of the listed documents, on pages 1-4 thereof; English-language Abstracts submitted with the

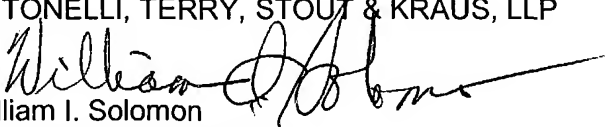
enclosed documents, and an English translation of relevant portions of the article discussed in the paragraph bridging pages 1 and 2 of Applicants' specification.

In view of all of the foregoing, it is respectfully submitted that all applicable requirements of 37 CFR § 1.97 and § 1.98 have been satisfied, in connection with present submission of the enclosed List. Accordingly, consideration of the listed documents, upon examination of the above-identified application, is respectfully requested.

To the extent necessary, Applicants petition for an extension of time under 37 CFR 1.136. Please charge any shortage in fees due in connection with the filing of this paper, including extension of time fees, to the Deposit Account No. 01-2135 (Case No. 503.41877VX1), and please credit any excess fees to such Deposit Account.

Respectfully submitted,

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<p>LIST OF ART CITED BY APPLICANT</p> <p>(PTO-1449)</p>	<p>ATTY. DOCKET NO.</p> <p>503.41877VX1</p>	<p>SERIAL NO.</p> <p>TBD</p>
	<p>APPLICANT</p> <p>A. Takahashi, et al.</p>	
	<p>FILING DATE</p> <p>Jun 25, 2003</p>	<p>GROUP</p> <p>TBD</p>

[illegible]

EXAMINER'S INITIALS	PATENT NO.	DATE	COUNTRY	CLASS	SUBCLASS	Translation/Abstract	
						Yes	No
	08-100107	4/16/1996	Japan			X	
	09-216938	8/19/1997	Japan			X	
	09-291131	11/11/1997	Japan			X	
	08-199045	8/6/1996	Japan			X	
	5-291438	11/5/1993	Japan			X	
	11-209579	8/3/1999	Japan			X	

	Hiroshi Kakiuchi, "New Epoxy Resin", Ch. 9, (1988) and English translation of the most relevant part	
EXAMINER	DATE CONSIDERED	